

AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the application:

LISTING OF CLAIMS:

Claims 1 to 8. (Canceled).

9. (New) A sensor system, comprising:

a thin-film sensor including a surface having at least one contact area;

a printed circuit board including a surface having at least one contact pad, the thin-film sensor arranged relative to the surface of the printed circuit board such that the surface of the thin-film sensor faces away from the surface of the printed circuit board; and

a conductive adhesive adapted to transmit sensor currents from the thin-film sensor to the printed circuit board, the conductive adhesive adhering to the contact area of the thin-film sensor and the contact pad on the surface of the printed circuit board.

10. (New) The sensor system according to claim 9, wherein the thin-film sensor is arranged as one of (a) a humidity sensor and (b) a moisture sensor.

11. (New) The sensor system according to claim 9, wherein the thin-film sensor is adapted to operate on a capacitive measuring principle.

12 ~~11~~. (New) The sensor system according to claim 9, wherein the thin-film sensor includes two contact areas, each contact area joined by the conductive adhesive to a corresponding contact pad of the printed circuit board.

13 ~~12~~. (New) The sensor system according to claim 9, further comprising a mounting adhesive arranged at least in one partial area between the thin-film sensor and the printed circuit board.

14 ~~13~~. (New) The sensor system according to claim 12, wherein a thermal conductivity of the mounting adhesive is greater than 0.3 W/(m·K).

15 ~~14~~. (New) A method for manufacturing a sensor system, comprising:
placing a thin-film sensor relative to a surface of a printed circuit board such that a surface of the thin-film sensor on which a contact area is arranged is facing away from the surface of the printed circuit board; and
bonding the thin-film sensor to the printed circuit board such that the contact area of the thin-film sensor is electrically connected by a conductive adhesive to a contact pad on the surface of the printed circuit board.

16 ~~15~~. (New) The method according to claim 14, further comprising applying a mounting adhesive on one of (a) the surface of the printed circuit board and (b) the surface of the thin-film sensor prior to the placing step.

17 ~~16~~. (New) A sensor system, comprising:
thin-film sensing means including a surface having at least one contact area;
printed circuit board means including a surface having at least one contact pad, the thin-film sensing means arranged relative to the surface of the printed circuit board means such that the surface of the thin-film sensing means faces away from the surface of the printed circuit board means; and
conductive adhering means for transmitting sensor currents from the thin-film sensing means to the printed circuit board means, the conductive adhering means adhering to the contact area of the thin-film sensing means and the contact pad on the surface of the printed circuit board means.